Notification Number:	20190129007		Notific	Notification Date: Feb. 15, 2019		
Title: LP875X Family RoHS Logo Change						
Customer Contact: PCN	Manager	Dept:	Quality Service	es		
Change Type:						
Assembly Site	· [[Design		Wafer Bump Site		
Assembly Process		Data Shee	et	Wafer Bump Material		
Assembly Materials			per change	Wafer Bump Process		
Mechanical Specification	n 🗌	Test Site	, e. e. a. ge	Wafer Fab Site		
Packing/Shipping/Labe		Test Proce	25	Wafer Fab Materials		
			Wafer Fab Process			
Notification Details						
Description of Change:						
Texas Instruments Incorporated is issuing an information only notification to announce the						
correction of the RoHS Logo from "G" (RoHS Compliant) to "X" (RoHS Exempt) for devices listed under Product Affected section.						
Flip Chip package (FCOL) fo	r I P875X	family of de	vices is consider	red exempt under BoHS		
exemption 15. See page 5						
exemption 15. See page 5		xemptions.				
Reason for Change:						
Material is RoHS Exempt du	ie to High	Pb Solder Pa	aste			
	-			bility (positive / negative):		
None.	-, - ,	, τ				
Changes to product identification resulting from this notification:						
Sample product shipping label (not actual product label)						
Symbol change: From Pb-Free						
Press INSTRUMENTS Made IN: Thailand 20C: Inst 1 /2600C/UNLIM Seal DT 12/07/18 OPT: TTEM: BL: 1A (L) TO: 1520						
To RoHS Exempt						
INSTRUMENTS MADE IN: Theiland 20C: MSL 1 /260C/UNLIM SEAL DT 12/07/18 BPT: 1TEM: 69 LBL: 1A (L) T0:1520						

Product Affected:			
LP87521CRNFRQ1	LP87524IRNFTQ1	LP87524ZRNFTQ1	LP87564ARNFRQ1
LP87521ERNFRQ1	LP87524JRNFRQ1	LP87525ARNFRQ1	LP8756DCRNFRQ1
LP87521ERNFTQ1	LP87524JRNFTQ1	LP87525JRNFRQ1	LP87564JRNFRQ1
LP87522BRNFRQ1	LP87524RRNFRQ1	LP87525JRNFTQ1	LP87565CRNFRQ1
LP87522BRNFTQ1	LP87524TRNFRQ1	LP87561FRNFRQ1	LP87565CRNFTQ1
LP87524ARNFRQ1	LP87524URNFRQ1	LP87562ARNFRQ1	
LP87524BRNFRQ1	LP87524URNFTQ1	LP87563ARNFRQ1	
LP87524BRNFTQ1	LP87524YRNFRQ1	LP87563JRNFRQ1	
LP87524FRNFRQ1	LP87524YRNFTQ1	LP875640RNFRQ1	
LP87524IRNFRQ1	LP87524ZRNFRQ1	LP875640RNFTQ1	



Date: 02 February 2018

EU RoHS Exemptions Expiring in July 2016

TI Products Requiring RoHS Exemptions:

The majority of Texas Instruments' (TI) IC components do not require RoHS exemptions. When TI IC components require an EU RoHS exemption, one of the following may apply:

- 7(a): Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
- 7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
- 7(c) IV: lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors
- Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages

Exemption extensions have been requested for all four exemptions listed above in Jan 2015 to meet the EU RoHS 18 month prior to expiration rule for these exemptions. For the first 3 listed, TI as well as the rest of the electronics industry, has been working diligently on possible solutions, but none exist today for the majority of these products. For exemption 15 this will likely not be extended broadly to all flip chip products since ICs on newer technologies smaller than 90nm or IC components less than 300mm2 have Pb-free replacements today. Technologies 90nm or greater or ICs 300mm2 or larger do not have Pb-free replacements.

TI started working with electronic industry consortia in June 2013 to consolidate the need for extending these exemptions beyond the current July 2016 expiration date. Though the exemptions 'expired' the end of July of 2016, there has not been a new RoHS Directive published with updated exemptions and expiration dates (or removal of any particular exemption). Since extensions have been filed for these exemptions they will remain in effect until the next EU RoHS Directive is published. TI continues to support the need for these exemptions being extended and will address product requirements and customer inquiries when the latest Directive is released as quickly as possible.

Sincerely,

Mal Friman

Mark Frimann TI SC Product Stewardship Management

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Revised: Feb 2018

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin team@list.ti.com